

TOSHIBA GATE TURN-OFF THYRISTOR REVERSE CONDUCTING TYPE

SGR3000GXH26

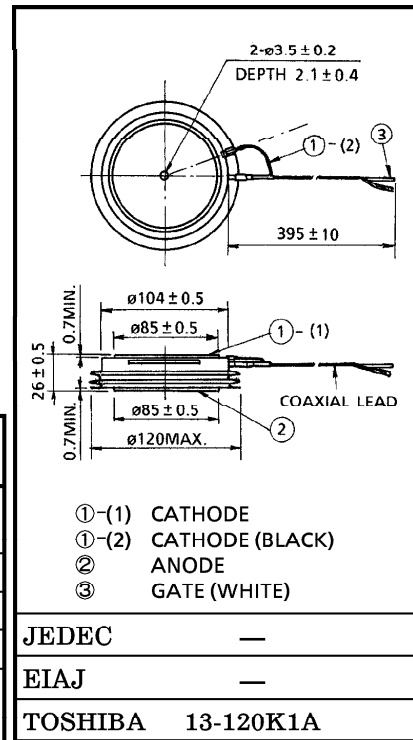
INVERTER APPLICATION

Unit in mm

- Repetitive Peak Off-State Voltage : $V_{DRM}=4500V$ (Note 1)
- R.M.S On-State Current : $I_T(RMS)=1200A$ ($T_f=77^\circ C$)
- R.M.S Reverse Current : $I_R(RMS)=900A$ ($T_f=77^\circ C$)
- Peak Turn-Off Current : $I_{TGQM}=3000A$
- Critical Rate of Rise of On-State Current : $di/dt=600A/\mu s$
- Critical Rate of Rise of Off-State Current : $dv/dt=1000V/\mu s$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Off-State Voltage (Note 1)	V_{DRM}	4500	V
Peak Turn-Off Current (Note 2)	I_{TGQM}	3000	A
R.M.S On-State Current (Note 3)	$I_T(RMS)$	1200	A
R.M.S Reverse Current (Note 3)	$I_R(RMS)$	900	A
Peak One Cycle Surge On-State Current (non repetitive, 10ms-width half sine waveform)	I_{TSM}	16000	A
Peak One Cycle Surge Reverse Current (non repetitive, 10ms-width half sine waveform)	I_{RSM}	14000	A
Critical Rate of Rise of On-State Current (Note 4)	di/dt	600	$A/\mu s$
Peak Forward Gate Current	I_{FGM}	100	A
Average Forward Gate Power Dissipation	$P_{FG}(AV)$	50	W
Average Reverse Gate Power Dissipation	$P_{RG}(AV)$	230	W
Peak Reverse Gate Power Dissipation	P_{RGM}	30	kW
R.M.S Gate Current (Note 5)	$I_G(RMS)$	42	A
Peak Reverse Gate Voltage (at Static)	V_{RGM}	16	V
Operating Junction Temperature Range	T_j	$-40\sim 125$	$^\circ C$
Storage Temperature Range	T_{stg}	$-40\sim 150$	$^\circ C$
Mounting Force	—	39.2 ± 4.9	kN



Weight : 1700g

Note 1 : $V_{GK} \leq -2V$ Note 2 : $V_{DM}=4000V$, $C_S=3.5\mu F$, $R_S=5\Omega$, $di_{GQ}/dt=50A/\mu s$, $L_S \leq 0.2\mu H$, $V_{DSP} \leq 1030V$ Note 3 : 50Hz Half Sine Waveform at $T_f=77^\circ C$ Note 4 : $V_D=1/2 V_{DRM}$, $I_{TM}=4000A$, $I_{GM} \geq 25A$ Note 5 : Ambient Temperature of coaxial gate-cathode lead $=90^\circ C$

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ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current	I_{DRM}	$V_{DRM} = \text{RATED}$, $V_{GK} = -2V$, $T_j = 125^\circ\text{C}$		—	—	150	mA
Repetitive Peak Reverse Gate Current	I_{RGM}	$V_{RGM} = 18V$, $T_j = 25^\circ\text{C}$		—	—	250	mA
Peak On-State Voltage	V_{TM}	$I_{TM} = 3000A$, $T_j = 125^\circ\text{C}$		—	—	4.0	V
Peak Reverse Voltage	V_{RM}	$I_{RM} = 3000A$, $T_j = 125^\circ\text{C}$		—	—	4.0	V
Gate Trigger Voltage	V_{GT}	$V_D = 24V$, $R_L = 0.1\Omega$	$T_j = -40^\circ\text{C}$	—	—	1.5	V
			$T_j = 25^\circ\text{C}$	—	—	1.20	
Gate Trigger Current	I_{GT}		$T_j = -40^\circ\text{C}$	—	—	8.0	A
			$T_j = 25^\circ\text{C}$	—	—	3.0	
Turn-On Delay Time	t_d	$V_D = 1/2 V_{DRM}$, $I_{TM} = 4000A$, $di/dt = 600A/\mu s$, $I_{GM} = 25A$, $di_G/dt = 10A/\mu s$, $T_j = 25^\circ\text{C}$		—	—	3	μs
Turn-On Time	t_{gt}			—	—	10	
Critical Rate of Rise of Off-State Voltage	dv/dt	$V_{DRM} = 2/3 \text{ RATED}$, $T_j = 125^\circ\text{C}$, $V_{GK} = -15V$		1000	—	—	$V/\mu s$
Storage Time	t_s	$V_{DM} = 4000V$, $I_{TGQ} = 3000A$, $V_D = 1/2 V_{DRM}$, $di_{GQ}/dt = 50A/\mu s$, $C_S = 3.5\mu F$, $R_S = 5\Omega$, $T_j = 125^\circ\text{C}$, $L_S \leq 0.2\mu H$		—	—	27.0	μs
Gate Turn-Off Time	t_{gq}			—	—	30.0	
Gate Turn-Off Current	I_{GQ}			—	—	800	A
Tail Time	t_{tail}			$(V_D = 1000V)$		115	μs
Commutating Critical Rate of Rise of Off-State Voltage	$dv/dt(c)$	$I_{RM} = 3500A$, $di_R/dt = 300A/\mu s$, $V_D = 1500V$, $V_{DM} = 3000V$, $C_S = 3.5\mu F$, $V_{GK} = -2V$, $T_j = 125^\circ\text{C}$		350	—	—	$V/\mu s$
Reverse Recovery Charge	Q_{rr}	$I_{RM} = 2000A$, $V_D = 500V$, $di_R/dt = 100A/\mu s$, $T_j = 125^\circ\text{C}$ (no snubber circuit)		—	—	2200	μC
Peak Reverse Recovery Current	I_{rr}			—	—	500	A
Thermal Resistance (Junction to Fin)	$R_{th(j-f)}$	DC	GTO Side	—	—	0.016	$^\circ C/W$
			Diode Side	—	—	0.025	

